



DDR4 DIMM

TE Internal #: 9-2199155-6

Double Data Rate (DDR) 4, Board-to-Bus Bar, 288 Position, Surface Mount, Vertical Module Orientation, DDR4 DIMM, DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: Double Data Rate (DDR) 4

Connector System: Board-to-Bus Bar

Number of Positions: 288

Termination Method to PCB: Surface Mount

Module Orientation: Vertical

[All DDR4 DIMM SOCKETS \(25\)](#)

Features

Mechanical Attachment

Connector Mounting Type	Board Mount
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Operation/Application

Circuit Application	Signal
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Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Bus Bar

Configuration Features

Number of Positions	288
Module Orientation	Vertical

Body Features

Ejector Type	Standard
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Contact Features

Contact Current Rating (Max)	.75 A
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Termination Features

Termination Method to PCB	Surface Mount
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Housing Features

Centerline (Pitch)	.85 mm[.033 in]
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Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
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Packaging Features

Packaging Method	Hard Tray
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Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

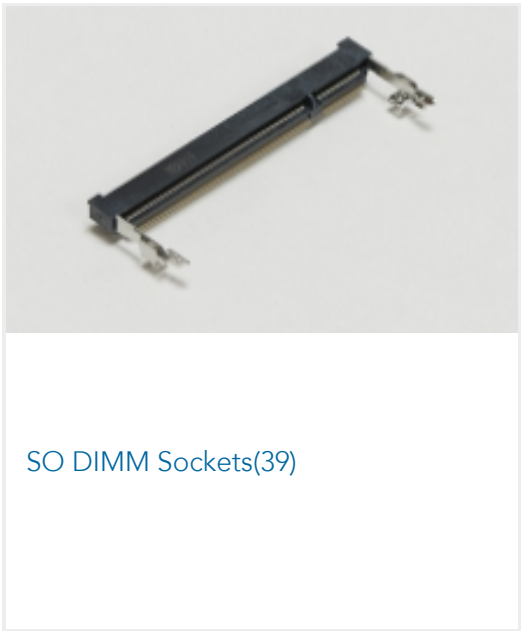
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series |

DDR4 DIMM



Customers Also Bought



Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_9-2199155-6_D.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_9-2199155-6_D.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_9-2199155-6_D.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications



Product Specification

English